

In partnership with

Plasma-Therm Technical Workshop: Plasma Etching

When: 21 September 21, 2016 (Wednesday), 9.00 am to 12:45pm

Location: Facoltà d'Ingegneria Civile e Industriale

Università Roma La Sapienza – Via Eudossiana, 18

This condensed workshop will focus on the fundamentals of plasma etching. Lectures will include the basics of plasma generation, reactors (RIE and ICP) and mechanisms for etching. The presentations will review state-of-the-art etching technology as applied to semiconductors, MEMS, and nanofabrication. Specific talks on compound semiconductor and deep silicon etching will complete the program.



**Event is free. Pre-registration requested before September 16, 2016.
(Please let us know if you cannot attend after registering – Thank you)
For general and registration enquiries, please contact the following email:**

strumenti@assing.it

Objectives

- Learn the fundamentals of plasma, reactors, and etching mechanisms
- Review etching technologies for deep silicon etching and compound semiconductors

Program

9:00 am	Welcome
9:15 am	Basics: Plasma, Reactors, and Etching Mechanisms
10:45 am	Compound Semiconductor Etching
11:45 am	Deep Reactive Ion Etching of Silicon
12:30 pm	Conclusion (Q&A encouraged during the presentations)

Coffee Break will be included during the workshop.



Speaker Information: David Lishan, Ph.D.

With a degree in Chemistry from UC Santa Cruz and Ph.D. from UC Santa Barbara in Solid State Electrical Engineering he has worked and published on a wide range of material, semiconductor, and chemistry R&D projects in the areas of lithography, photochemistry, x-ray mask fabrication, PVD, and plasma processing. During 18 years at Plasma-Therm, he has had business unit

management and worldwide marketing responsibilities as well as managing the development of recently released plasma dicing product. As a Principal Scientist and Director in Technical Marketing, he has recently organized and presented plasma processing workshops at leading institutions throughout the world. His primary focus is on the application of plasma processing for R&D, MEMS, photonics, data storage, power, and compound semiconductor applications. He holds two patents and has over 60 publications and conference presentations.